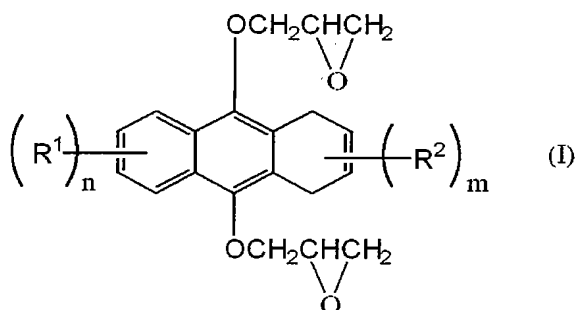


ABSTRACT

Provided is a sealant epoxy-resin molding material according to the present invention comprising an epoxy resin (A) and a hardening agent (B), wherein the epoxy resin (A) includes a compound represented by the following General Formula (I). The sealant epoxy-resin molding material is superior in reliability such as flame resistance, moldability, reflow resistance, moisture resistance and high-temperature storage stability, and others and favorably used for sealing of VLSI, and an electronic component device containing an element sealed with the molding material.

(Formula 1)



(in General Formula (I), R^1 represents a group selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms and the groups R^1 may be the same or different from each other; n is an integer of 0 to 4; R^2 represents a group selected from substituted or unsubstituted hydrocarbon group having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy group having 1 to 12 carbon atoms, and the groups R^2 may be the same or different from each other; and m is an integer of 0 to 6).